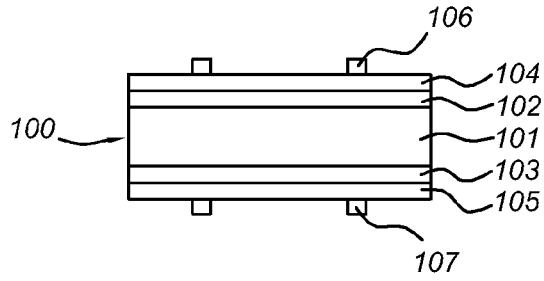
Fig 1


106
104
102
100
101
103
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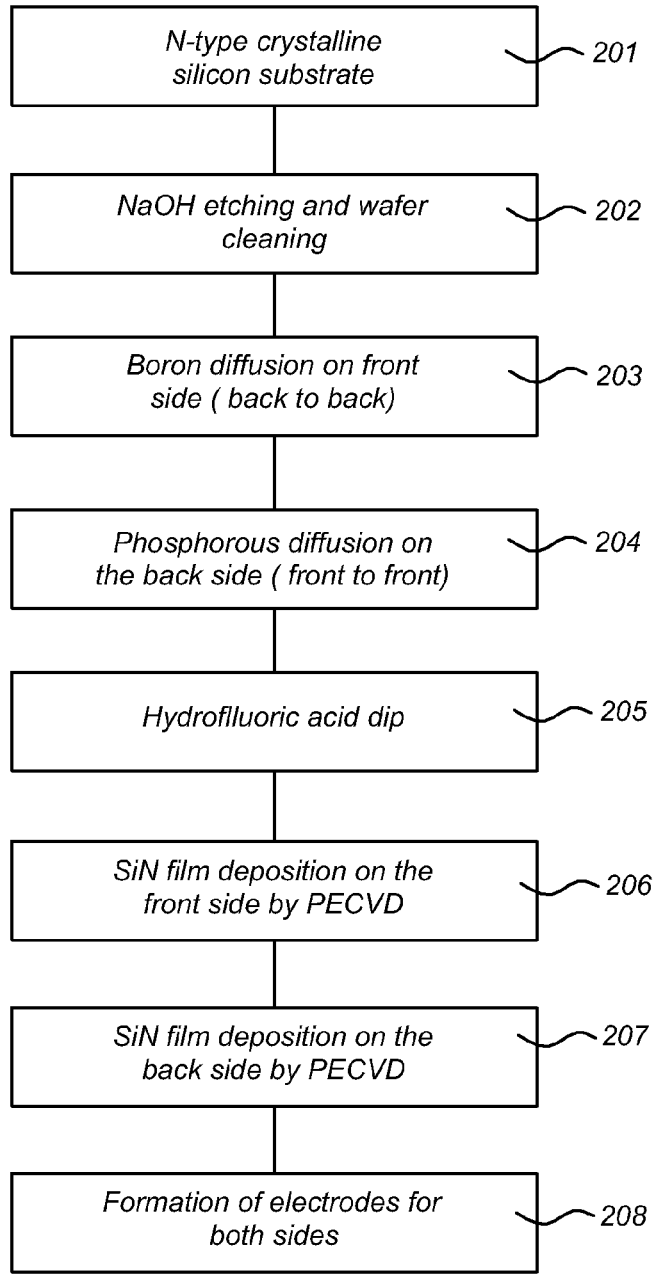
107

Fig 2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